

# SSM6J50TU

## ○ High Current Switching Applications

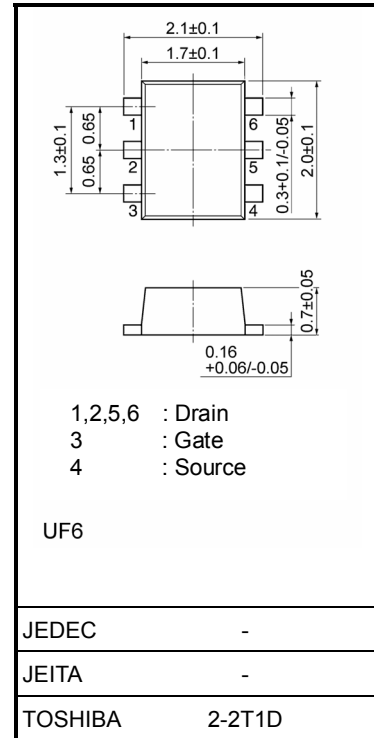
Unit: mm

- Compact package suitable for high-density mounting
- Low on-resistance:  $R_{on} = 205\text{m}\Omega$  (max) (@ $V_{GS} = -2.0\text{ V}$ )  
 $R_{on} = 100\text{m}\Omega$  (max) (@ $V_{GS} = -2.5\text{ V}$ )  
 $R_{on} = 64\text{m}\Omega$  (max) (@ $V_{GS} = -4.5\text{ V}$ )

## Maximum Ratings ( $T_a = 25^\circ\text{C}$ )

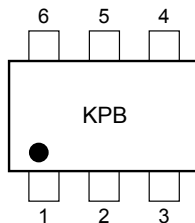
Characteristics	Symbol	Rating	Unit
Drain-Source voltage	$V_{DS}$	-20	V
Gate-Source voltage	$V_{GSS}$	$\pm 10$	V
Drain current	DC	$I_D$	A
	Pulse	$I_{DP}$	
Drain power dissipation	$P_D$ (Note1)	500	mW
Channel temperature	$T_{ch}$	150	$^\circ\text{C}$
Storage temperature range	$T_{stg}$	$-55\sim 150$	$^\circ\text{C}$

Note1: Mounted on FR4 board.  
 (25.4 mm × 25.4 mm × 1.6 t, Cu Pad: 645 mm<sup>2</sup>)

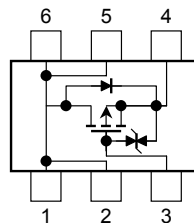


Weight: 7 mg (typ.)

## Marking



## Equivalent Circuit



## Handling Precaution

When handling individual devices that are not yet mounted on a circuit board, be sure that the environment is protected against electrostatic discharge. Operators should wear anti-static clothing, and containers and other objects that come into direct contact with devices should be made of anti-static materials.

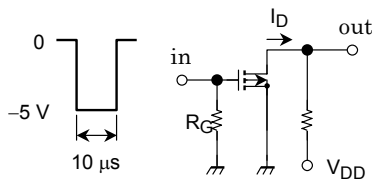
## Electrical Characteristics (Ta = 25°C)

Characteristics	Symbol	Test Condition	Min	Typ.	Max	Unit
Gate leakage current	$I_{GSS}$	$V_{GS} = \pm 8 \text{ V}, V_{DS} = 0$	—	—	$\pm 10$	$\mu\text{A}$
Drain-Source breakdown voltage	$V_{(BR)DSS}$	$I_D = -10 \text{ mA}, V_{GS} = 0$	-20	—	—	V
	$V_{(BR)DSX}$	$I_D = -10 \text{ mA}, V_{GS} = +10 \text{ V}$	-10	—	—	
Drain cut-off current	$I_{DSS}$	$V_{DS} = -20 \text{ V}, V_{GS} = 0$	—	—	-10	$\mu\text{A}$
Gate threshold voltage	$V_{th}$	$V_{DS} = -10 \text{ V}, I_D = -0.2 \text{ mA}$	-0.5	—	-1.2	V
Forward transfer admittance	$ Y_{fs} $	$V_{DS} = -10 \text{ V}, I_D = -1.5 \text{ A}$ (Note2)	3.1	6.2	—	S
Drain-Source on-resistance	$R_{DS(ON)}$	$I_D = -1.5 \text{ A}, V_{GS} = -4.5 \text{ V}$ (Note2)	—	49	64	$\text{m}\Omega$
		$I_D = -1.5 \text{ A}, V_{GS} = -2.5 \text{ V}$ (Note2)	—	73	100	
		$I_D = -1.5 \text{ A}, V_{GS} = -2.0 \text{ V}$ (Note2)	—	105	205	
Input capacitance	$C_{iss}$	$V_{DS} = -10 \text{ V}, V_{GS} = 0, f = 1 \text{ MHz}$	—	800	—	pF
Reverse transfer capacitance	$C_{rss}$	$V_{DS} = -10 \text{ V}, V_{GS} = 0, f = 1 \text{ MHz}$	—	120	—	pF
Output capacitance	$C_{oss}$	$V_{DS} = -10 \text{ V}, V_{GS} = 0, f = 1 \text{ MHz}$	—	160	—	pF
Switching time	Turn-on time	$t_{on}$	—	15	—	ns
	Turn-off time	$t_{off}$		51		

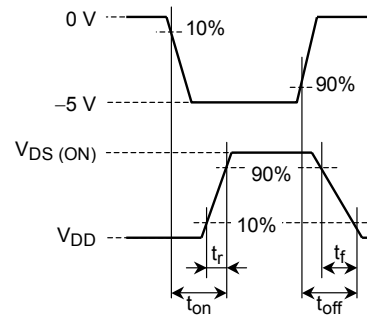
Note2: Pulse test

## Switching Time Test Circuit

(a) Test Circuit



$V_{DD} = -10 \text{ V}$   
 $R_G = 4.7 \Omega$   
 $\text{D.U.} \leq 1\%$   
 $V_{IN}: t_r, t_f < 5 \text{ ns}$   
 Common Source  
 $T_a = 25^\circ\text{C}$

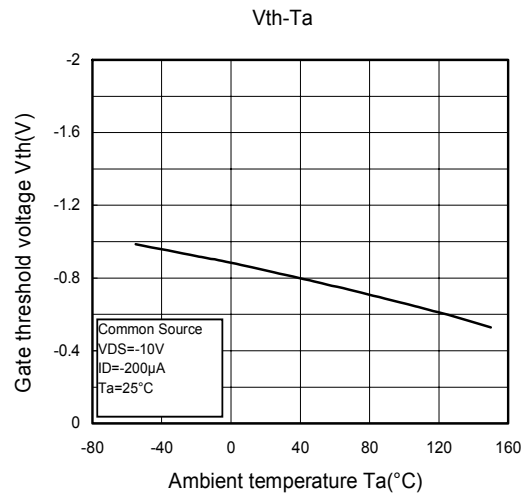
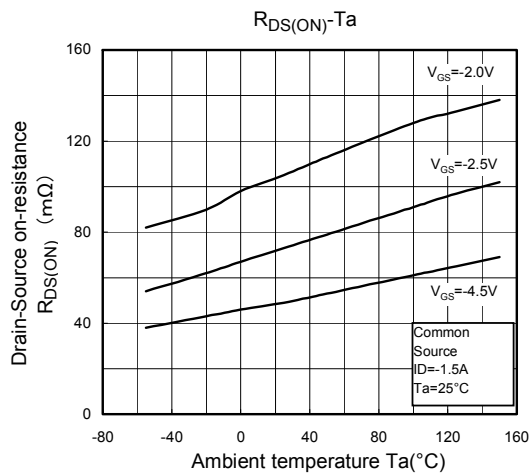
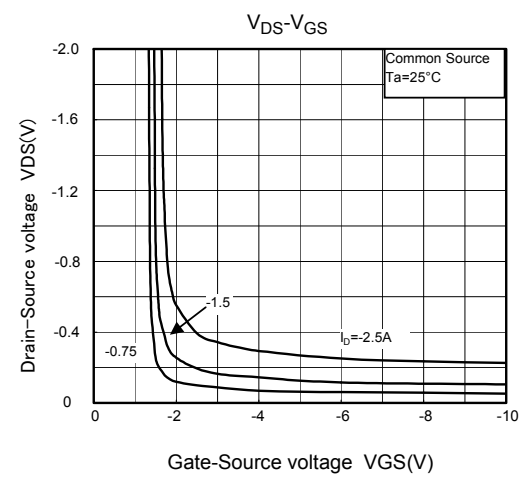
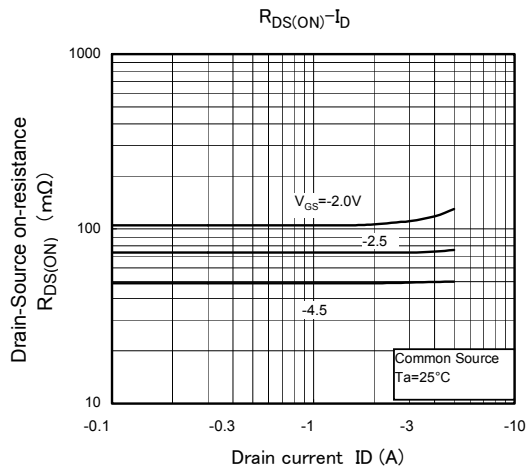
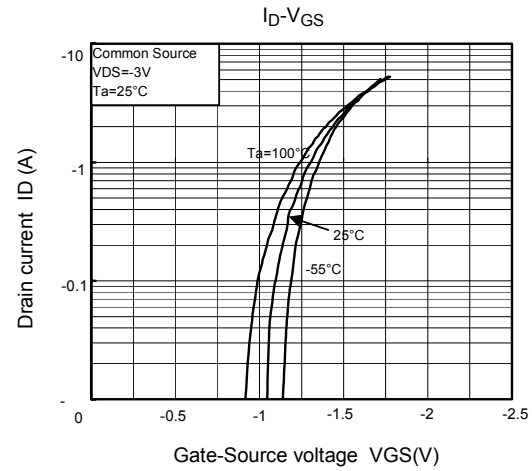
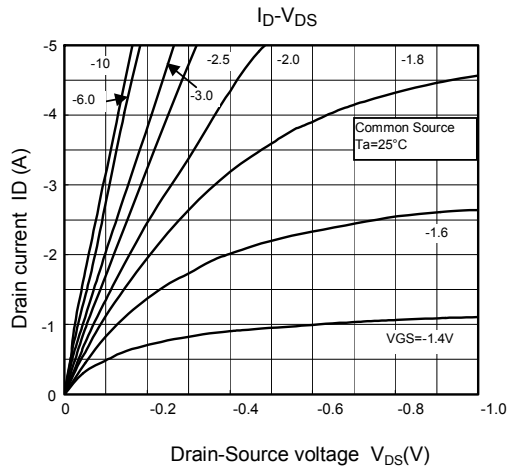
(b)  $V_{IN}$ (c)  $V_{OUT}$ 

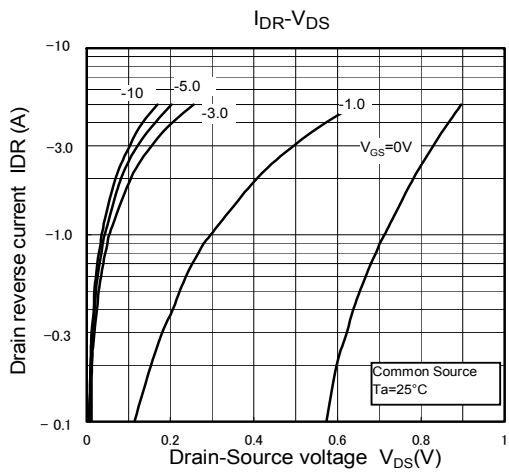
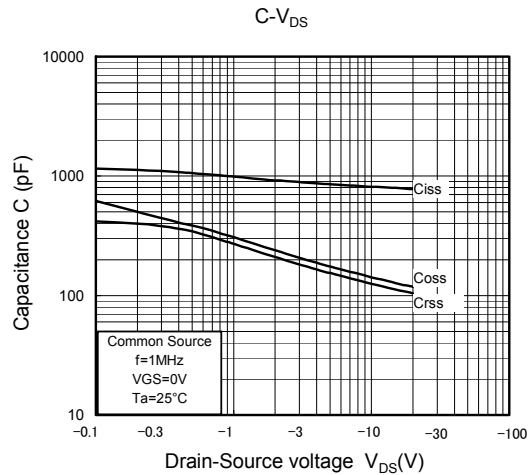
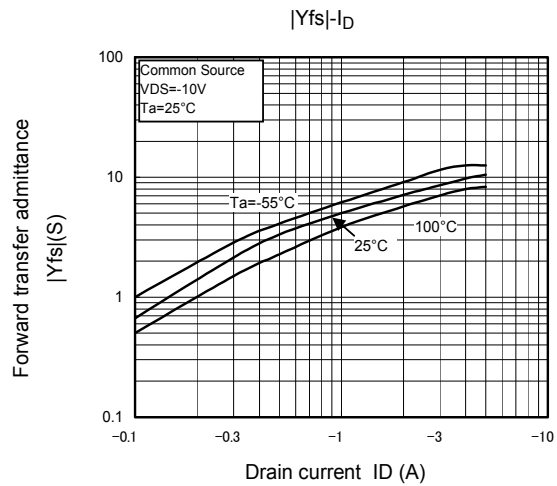
## Precaution

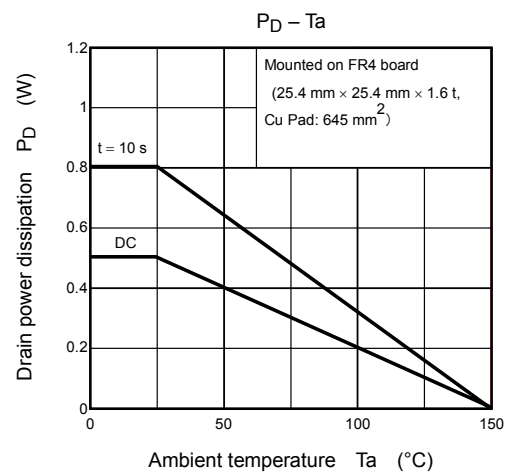
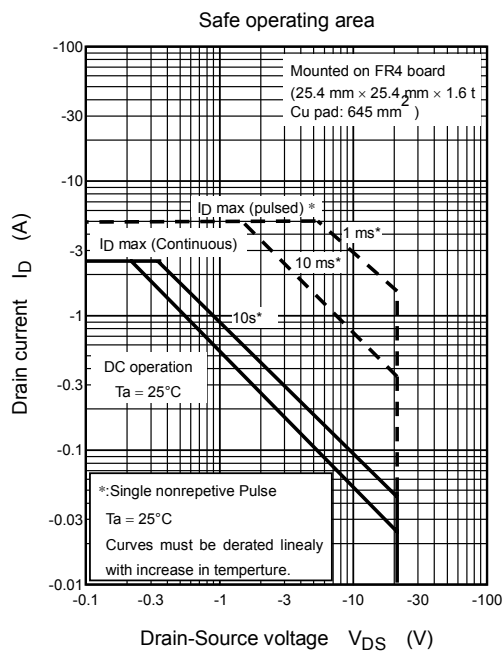
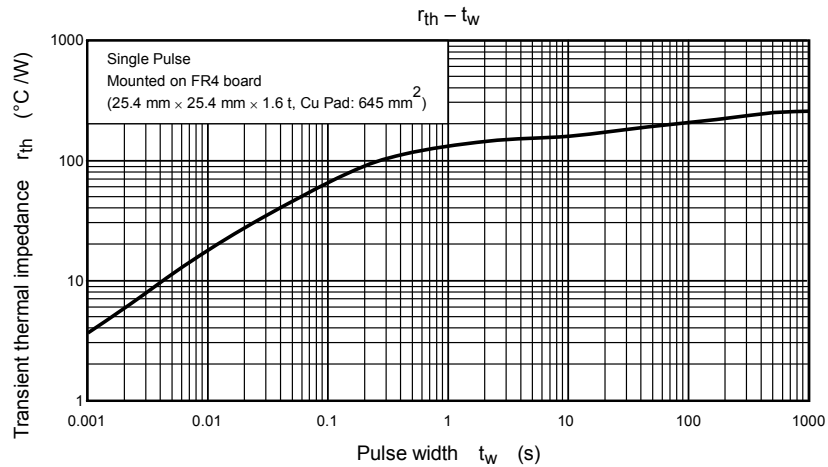
$V_{th}$  can be expressed as the voltage between gate and source when the low operating current value is  $I_D = -200 \mu\text{A}$  for this product. For normal switching operation,  $V_{GS(on)}$  requires a higher voltage than  $V_{th}$  and  $V_{GS(off)}$  requires a lower voltage than  $V_{th}$ .

(The relationship can be established as follows:  $V_{GS(off)} < V_{th} < V_{GS(on)}$ )

Be sure to take this into consideration when using the device. The  $V_{GS}$  recommended voltage for turning on this product is -2.0 V or higher.







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